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Novel Materials and Technologies for Sustainable, Smart and Active Food Packaging

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Message from the Guest Editors

Global pollution, oil scarcity and new food safety and quality requirements have led to the development of different sustainable materials for food packaging applications. Packaging has a great impact on sustainability due to its direct or indirect use in the food chain and food waste. During the last decade, food packaging has been developing new smart and active materials that extend shelf life; maintain quality, safety, and integrity; and avoid microorganisms' proliferation and food oxidation reactions by incorporating active substances which interact with the inner environment and monitor the state of the packaged food products.

Papers on any topics related to the fundamental understanding and recent advances in the field of Smart and Active Packaging based on sustainable strategies are highly recommended for publication in the Special Issue o f*Applied Sciences* titled "Novel Materials and Technologies for Sustainable, Smart and Active Food Packaging".

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Keywords.

biopolymers

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agroindustrial by-pro

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Editor-in-Chief

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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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